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(54) Title: IMPROVEMENTS IN OR RELATING TO SOLDERS

(57) Abstract: A lead-free solder, comprising: from around 96.8% to around 99.3% tin; from 0.2% to 3.0% copper; from 0.02% to around 0.12% silicon, and optionally 0.005% to 0.01% P and/or 0.0005%-0.01 Ge.



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